	© Copyright 2005. I cs INDUSTRIES	PC, Bannockb	ourn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarat	ion of th encompa	ne substances asses all lowe	within the er level mat	manufactur erials for wl	er listed it hich the m	em. Note: anufacture	if the item is an as er has engineering	ssembly with low responsibility.
752-21.1					Form Type Distribute					eous Materia	terials and Mfg Information				
upplie	r Information														
Company name* Com				Company unique ID			Unique ID Authority					Response Date*			
nsemi												2023-06-08			
ontact N	Name	Title - Contact				Phone - Contact*				Email - Contact*					
Product-	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative				Phone - Representative*				Email - Representative*					
roduct-	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item Number   LC821621-E		Number Mfr Item Name				Effective Date Version Manufacturing S   2023-06-08 PHM		Manufactu	unufacturing Site Weight*		UOM	Unit Type		
			21-Е	VoIP Processor						2300.0		mg	Each		
Ianufa	ncturing Proccess Informa	tion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperat	ire Num	ber of Reflow Cyc	cles	
Matte Tin (Sn) - annealed		CU Alloy 4			<b>260</b> C		30 sec		second	ls 3					
omments	s														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl late (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	27.15	mg	Supplier	Silicon (Si)	7440-21-3		27.055	mg
			Supplier	Polyimide	Proprietary Data		0.095	mg
Die Attach	6.37	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		5.3508	mg
			Supplier	Silver (Ag)	7440-22-4		1.0192	mg
Lead Frame	666.0	mg	Supplier	Silver (Ag)	7440-22-4		16.5834	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.9324	mg
			Supplier	Silicon (Si)	7440-21-3		4.1958	mg
			В	Nickel (Ni)	7440-02-0		19.4472	mg
			Supplier	Copper (Cu)	7440-50-8		624.8412	mg
Mold Compound-Black	1590.58	mg		Phenolic Resin	proprietary data		63.6232	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		103.3877	mg
			Supplier	Carbon Black (C)	1333-86-4		4.7717	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1418.7972	mg
Plating	5.0	mg	Supplier	Tin (Sn)	7440-31-5		5	mg
Wire Bond - Au	4.9	mg	Supplier	Gold (Au)	7440-57-5		4.9	mg